# **MA2YD21**

#### Silicon epitaxial planar type

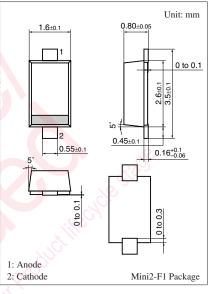
For high frequency rectification

#### Features

- Forward current (Average)  $I_{F(AV)} = 1$  A rectification is possible
- Low forward voltage:  $V_F < 0.4 V$

Parameter	Symbol	Rating	Unit		
Reverse voltage	V <sub>R</sub>	15	V		
Repetitive peak reverse voltage	V <sub>RRM</sub>	15	V		
Forward current (Average) *1	I <sub>F(AV)</sub>	1.0	A		
Non-repetitive peak forward surge current *2	I <sub>FSM</sub>	3	А		
Junction temperature	Tj	125	°C		
Storage temperature	T <sub>stg</sub>	-55 to +125	°C		





Marking Symbol: 2X

Note) \*1: Mounted on an alumina PC board

\*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

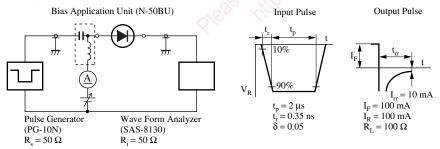
#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V <sub>F</sub>	I <sub>F</sub> =1A	50	SOL	0.4	V
Reverse current	IR	$V_R = 6 V$		0-	1.5	mA
Terminal capacitance	Ct	$V_R = 0 V, f = 1 MHz$	20	180		pF
Reverse recovery time *	t <sub>rr</sub>	$I_F = I_R = 100 \text{ mA}$		12		ns
		$I_{rr} = 10 \text{ mA}, R_L = 100 \Omega$				

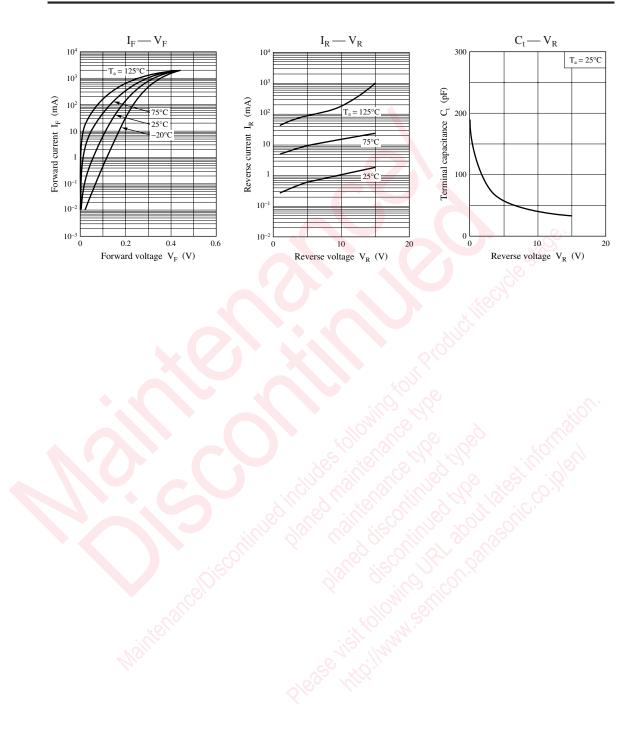
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

3. \*: t<sub>rr</sub> measurement circuit



### **Panasonic**



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